Fig. 1

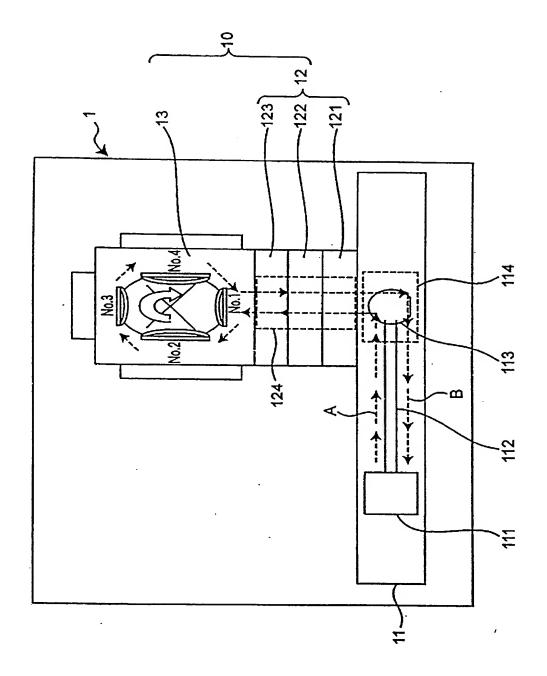


Fig. 2

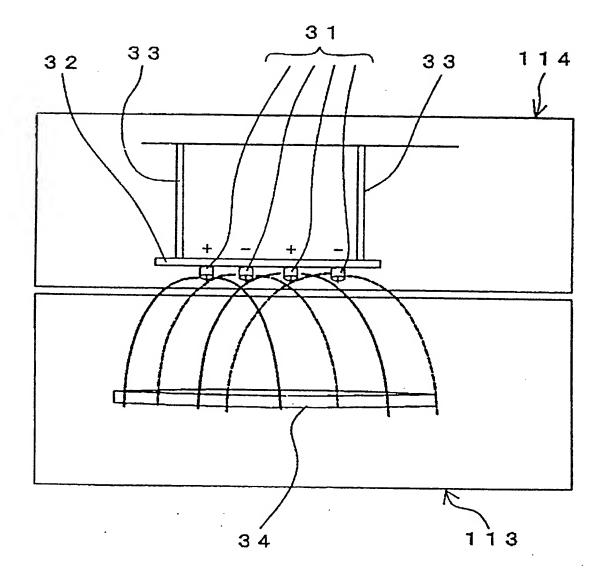
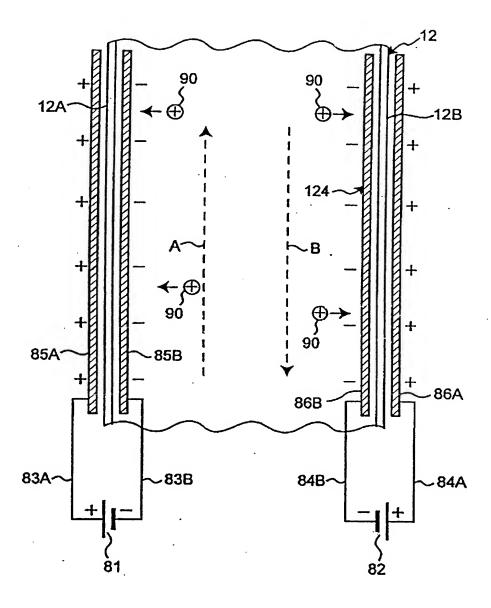
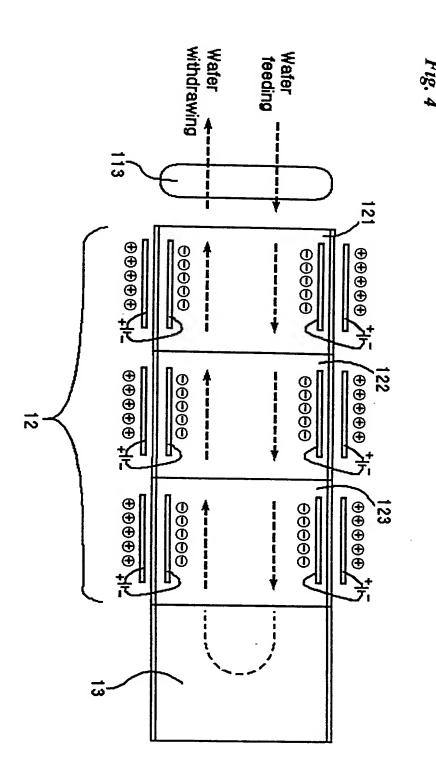


Fig. 3





DEVICE WAFER PROCESSING

To clean device wafers

To set the wafers in a cassette-loading unit

To increase pressure of the LOC up to atmospheric pressure

To sequentially convey the wafers to a waiting-accommodation unit

To neutralize the wafers by an inonizer

To accommodate entire wafers in the LOC

To reduce pressure of the LOC from atmospheric pressure

To accommodate entire wafers in the BUC

To sequentially convey the wafers to the SPC to be subjected to sputtering process and convey back to the BUC

To accommodate entire wafers in the BUC

To accommodate entire wafers in the LOC

To increase pressure of the LOC up to atmospheric pressure

To sequentially load the wafers in the cassette-loading unit

To complete the device wafer processing

To convey the device to subsequent process

PARTICLE COLLECTION PROCESSING

Normally, to adsorb particles in a vacuum container unit by electrostatic force by means of a charging means



To prevent the adherence of particles to a surface of a device wafer

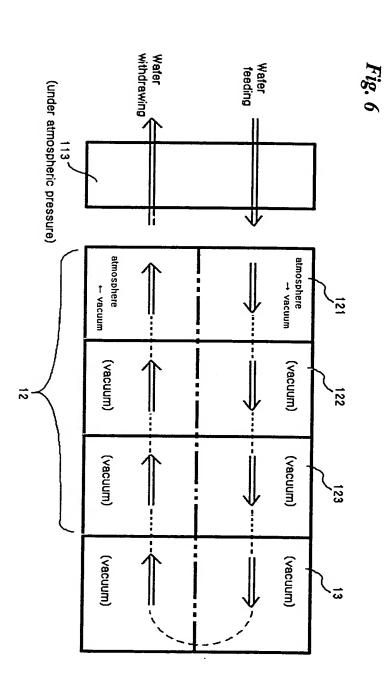


Fig. 7

